

HIGH FREQUENCY

ELECTRONICS

2019

Issue	Featured and New Product Coverage	Important Industry Events
January	Antennas, Cable Assemblies, Couplers, Test and Measurement	IEEE Radio & Wireless Symposium , Orlando January 20 - 23, 2019 DesignCon , Santa Clara January 29 - 31, 2019
February	Design Tools, Power Amplifiers Filters, Mil-Aero Products	
March	Passive Components- Attenuators, DC Blocks/Bias Tees	NAB , Las Vegas April 6 - 11, 2019 WAMICON , Cocoa Beach, FL April 8 - 9, 2019
April	Test & Measurement Tools Cable Assemblies, Integrated Assemblies	Satellite 2019 , Washington DC May 6 - 9, 2019
May	Active Components, Switches, Mixers, Phase Shifters, IMS2018 Show Issue	IMS 2019 , Boston June 2 - 7, 2019
June	Frequency Control Components, Low Loss Cables, Design Tools Update	IEEE EMC + SIPI , New Orleans July 22 - 26, 2019
July	Passive Components, Isolators, Circulators, Connectors, Antennas	
August	Defense Electronics EDA, Automated Test, Test Cables, Signal Generators	IEEE AUTOTESTCON , National Harbor, MD September 9 - 12, 2019
September	Millimeter Connectors and Components, Detectors	EuMW 2019 , Paris September 29 - October 4, 2019 MILCOM 2019 , location TBD October 2019 (date TBD)
October	Circuit Materials, Interconnects, Base Station Products, Network Analyzers, Mil-Spec Products	AOC , Washington, DC October 28 - 30, 2019
November	Coaxial Adapters, Low Noise Amplifiers, Modular Test Equipment	
December	Passive Components, Couplers and Power Dividers, Crystal Oscillators, VCOs, YIG Oscillators	IEEE Radio and Wireless Symposium , location TBD January 2020 (date TBD)

Additional technical articles can be published in each issue, covering other topics

AD CLOSING DATES: 15th of the prior month (next business day if weekend)

AD MATERIAL DEADLINE: 20th of the prior month.

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Editorial Submissions

Regular Columns

Meetings & Events, In the News, Design Notes, High Frequency Applications

Press Releases

Press releases for our informational columns should be sent by the first of the month prior to the desired publication date (e.g., April 1 for the May issue). Late-breaking news can be accommodated, but please advise the editors of urgent items by telephone or e-mail.

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Article Contributions

We encourage the submission of technical articles, application notes and other editorial contributions. These may be on the topics noted above, or any other subject of current interest. Contact us with article ideas:

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